V_{RRM}	=	4500 V
I_{FAVM}	=	650 A
I_{FSM}	=	16 kA
V_{F0}	=	1.4 V
r_F	=	1 mΩ
V_{DClink}	=	2800 V

Fast Recovery Diode

5SDF 07F4501

Doc. No. 5SYA1107-03 Sep. 01

- **Patented free-floating silicon technology**
- **Low on-state and switching losses**
- **Optimized for use as freewheeling diode in GTO converters with high DC link voltages**
- **Standard press-pack housing, hermetically cold-welded**
- **Cosmic radiation withstand rating**

Blocking

V_{RRM}	Repetitive peak reverse voltage	4500 V	Half sine wave, t_P = 10 ms, f = 50 Hz	
I_{RRM}	Repetitive peak reverse current	≤ 50 mA	$V_R = V_{RRM}$, T_j = 125°C	
V_{DClink}	Permanent DC voltage for 100 FIT failure rate	2800 V	100% Duty	Ambient cosmic radiation at sea level in open air.
V_{DClink}	Permanent DC voltage for 100 FIT failure rate	V	5% Duty	

Mechanical data (see Fig. 12)

F_m	Mounting force	min.	20 kN	
		max.	24 kN	
a	Acceleration: Device unclamped Device clamped		 50 m/s^2 200 m/s^2	
m	Weight		0.46 kg	
D_S	Surface creepage distance	≥	33 mm	
D_a	Air strike distance	≥	20 mm	

On-state (see Fig. 2, 3)

I_{FAVM}	Max. average on-state current	650 A	Half sine wave, T_c = 85°C	
I_{FRMS}	Max. RMS on-state current	1000 A		
I_{FSM}	Max. peak non-repetitive surge current	16 kA	tp = 10 ms	Before surge: $T_c = T_j$ = 125°C
		44 kA	tp = 1 ms	
$\int I^2dt$	Max. surge current integral	$1.28 \cdot 10^6$ A^2s	tp = 10 ms	After surge: $V_R \approx 0$ V
		$0.8 \cdot 10^6$ A^2s	tp = 1 ms	
V_F	Forward voltage drop	≤ 2.7 V	I_F = 1250 A	T_j = 125°C
V_{F0}	Threshold voltage	1.4 V	Approximation for	
r_F	Slope resistance	1 mΩ	I_F = 400…2000 A	

Turn-on (see Fig. 4, 5)

V_{fr}	Peak forward recovery voltage	≤ 74 V	di/dt = 500 A/µs, T_j = 125°C

Turn-off (see Fig. 6 to 11)

I_{rr}	Reverse recovery current	≤ 600 A	di/dt = 300 A/µs, I_F = 700 A, T_j = 125°C, V_{RM} = 4500 V, C_S = 3µF (GTO snubber circuit)
Q_{rr}	Reverse recovery charge	≤ 1900 µC	
E_{rr}	Turn-off energy	≤ 1 J	

Thermal (see Fig. 1)

T_j	Operating junction temperature range	-40...125°C		
T_{stg}	Storage temperature range	-40...125°C		
R_{thJC}	Thermal resistance junction to case	≤ 40 K/kW	Anode side cooled	F_m = 20… 24 kN
		≤ 40 K/kW	Cathode side cooled	
		≤ 20 K/kW	Double side cooled	
R_{thCH}	Thermal resistance case to heatsink	≤ 10 K/kW	Single side cooled	
		≤ 5 K/kW	Double side cooled	

Analytical function for transient thermal impedance.

$$Z_{thJC}(t) = \sum_{i=1}^{n} R_i(1 - e^{-t/\tau_i})$$

i	1	2	3	4
R_i(K/kW)	11.83	4.26	1.63	2.28
τ_i(s)	0.432	0.071	0.01	0.0054
F_m = 20… 24 kN Double side cooled				

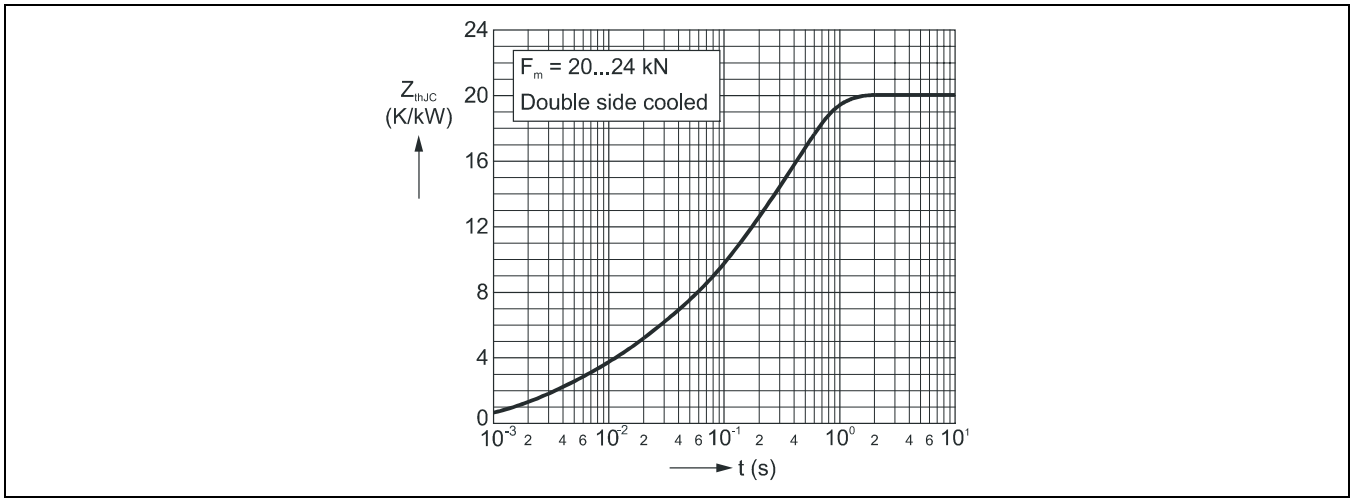

Fig. 1 Transient thermal impedance (junction-to-case) vs. time in analytical and graphical form (max. values).

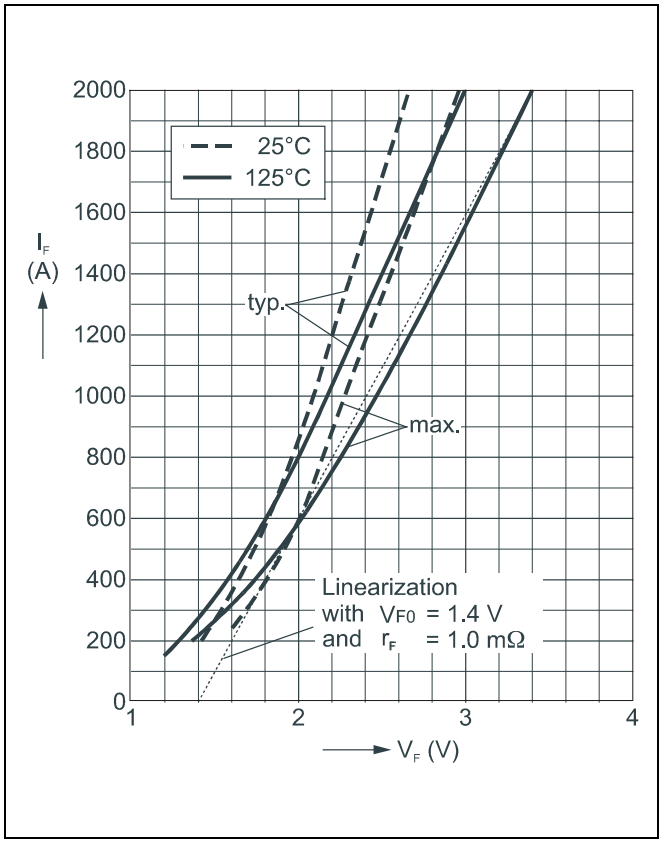

Fig. 2 Forward current vs. forward voltage (typ. and max. values) and linear approximation of max. curve at 125°C.

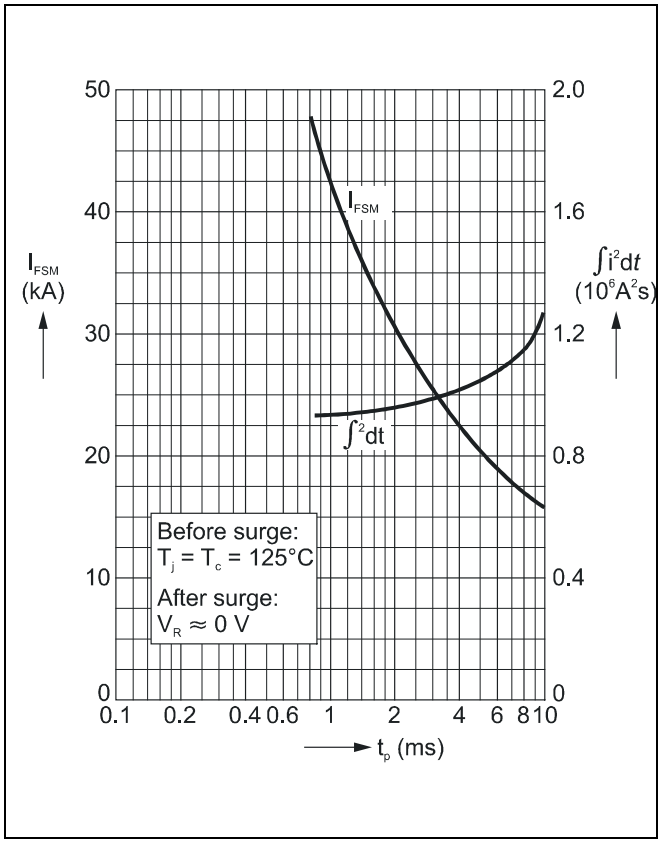

Fig. 3 Surge current and fusing integral vs. pulse width (max. values) for non-repetitive, half-sinusoidal surge current pulses.

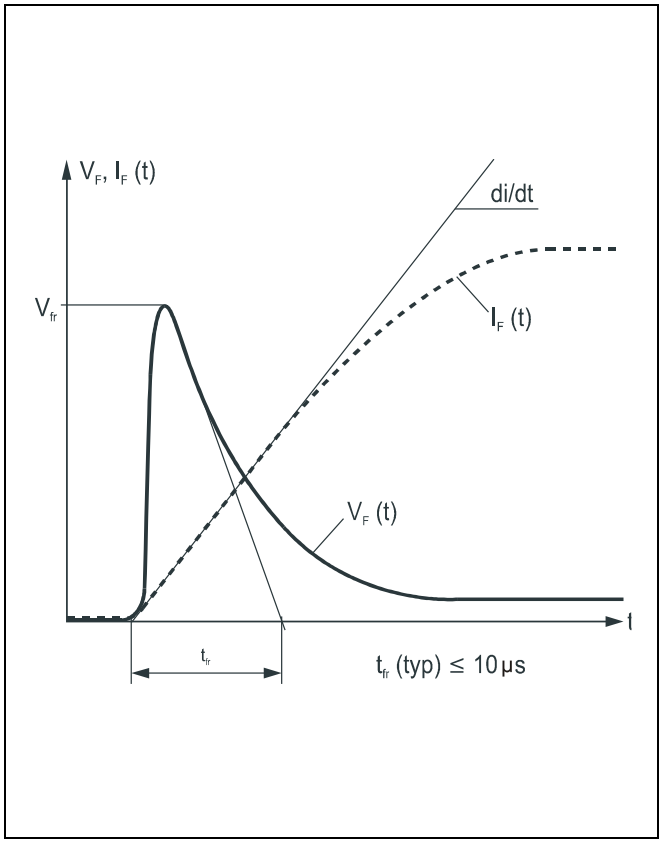

Fig. 4 Typical forward voltage waveform when the diode is turned on with a high di/dt.

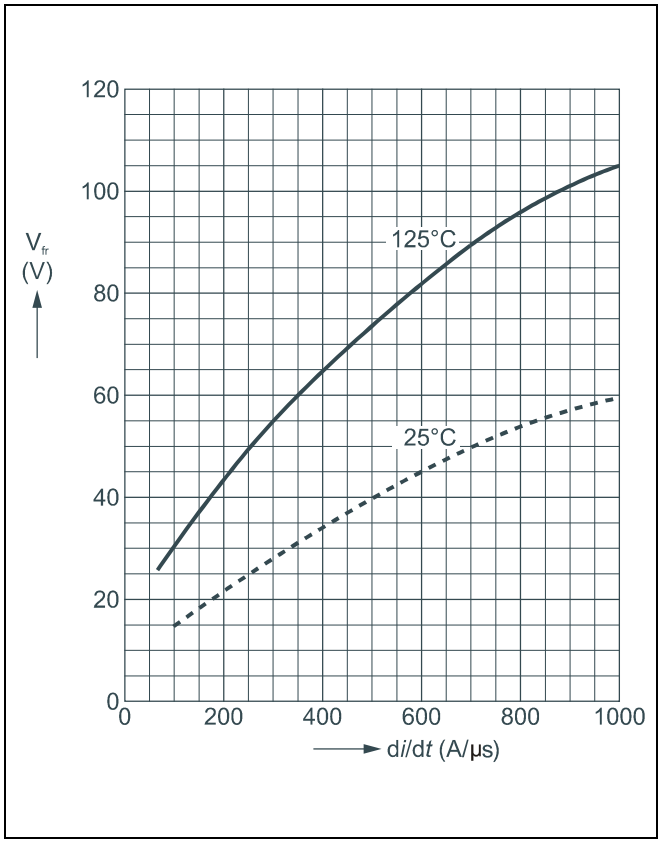

Fig. 5 Forward recovery voltage vs. turn-on di/dt (max. values).

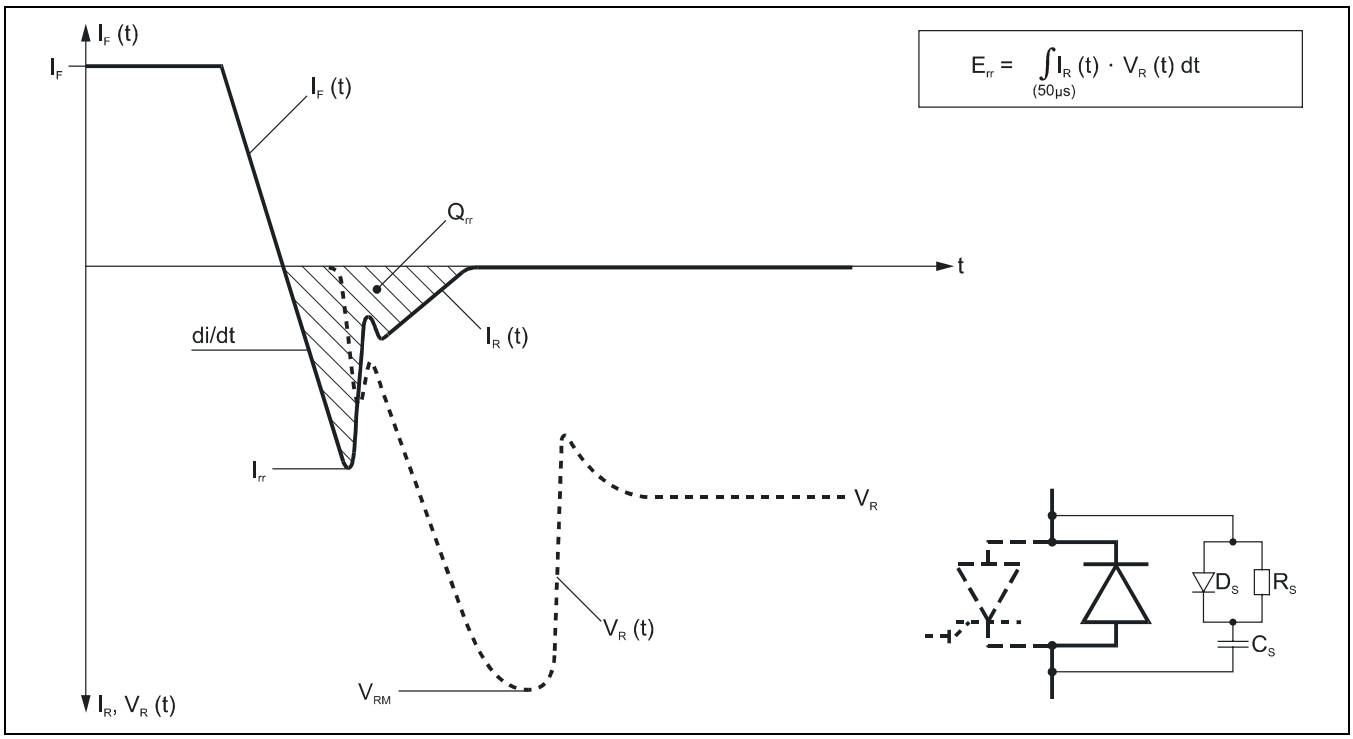

Fig. 6 Typical current and voltage waveforms at turn-off when the diode is connected to an RCD snubber, as often used in GTO circuits.

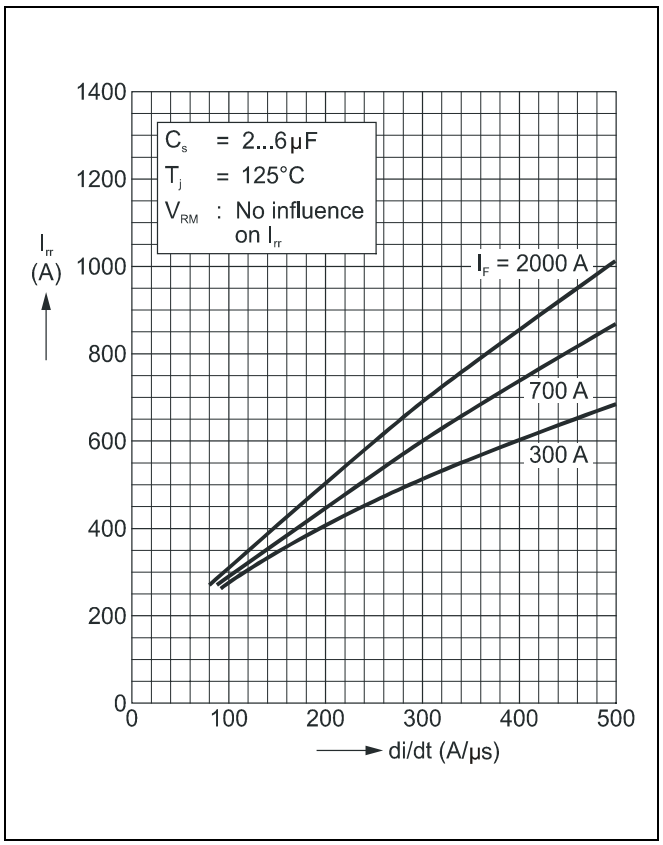

Fig. 7 Reverse recovery current vs. turn off di/dt (max. values).

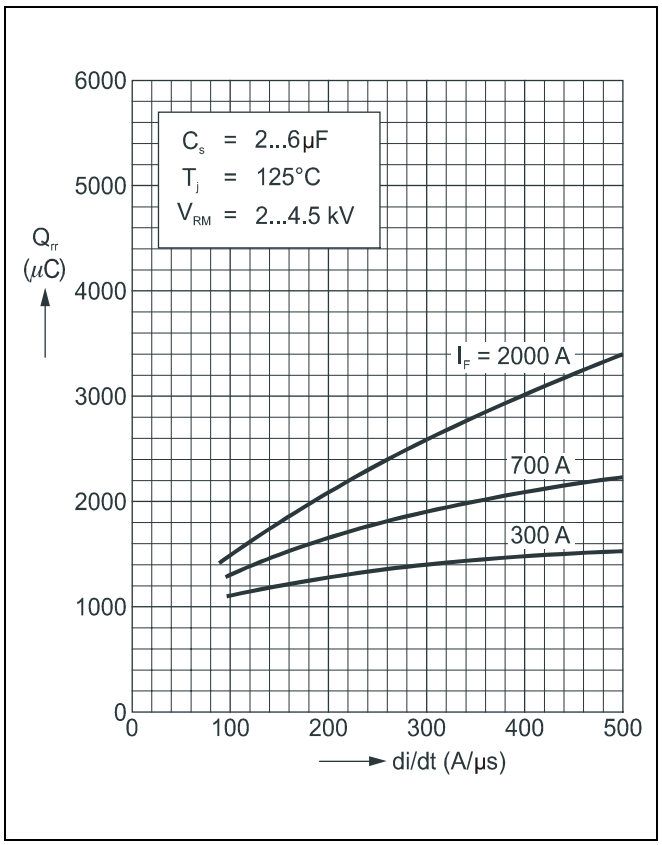

Fig. 8 Reverse recovery charge vs. turn off di/dt (max. values).

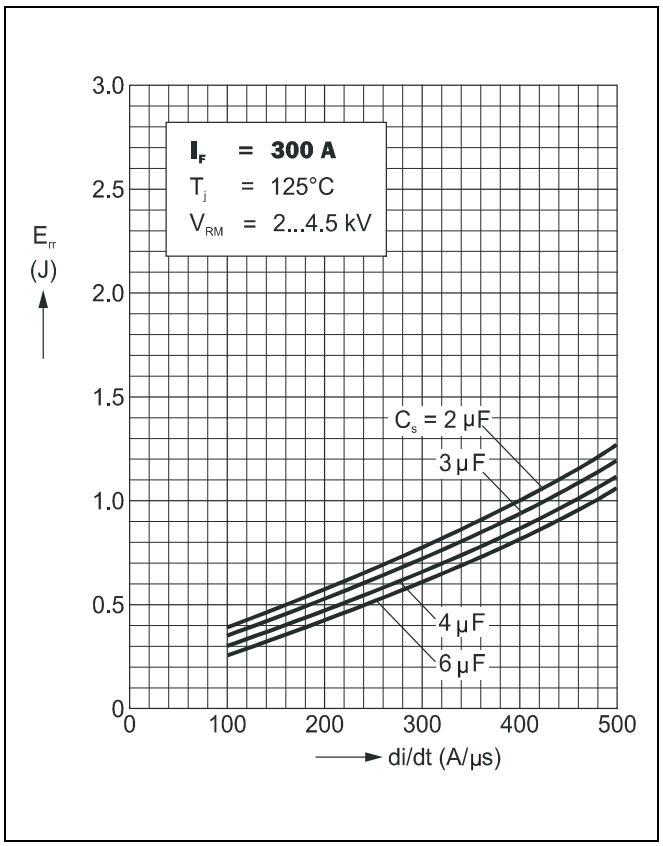

Fig. 9 Turn-off energy vs. turn-off di/dt for I_F = 300 A (max. values).

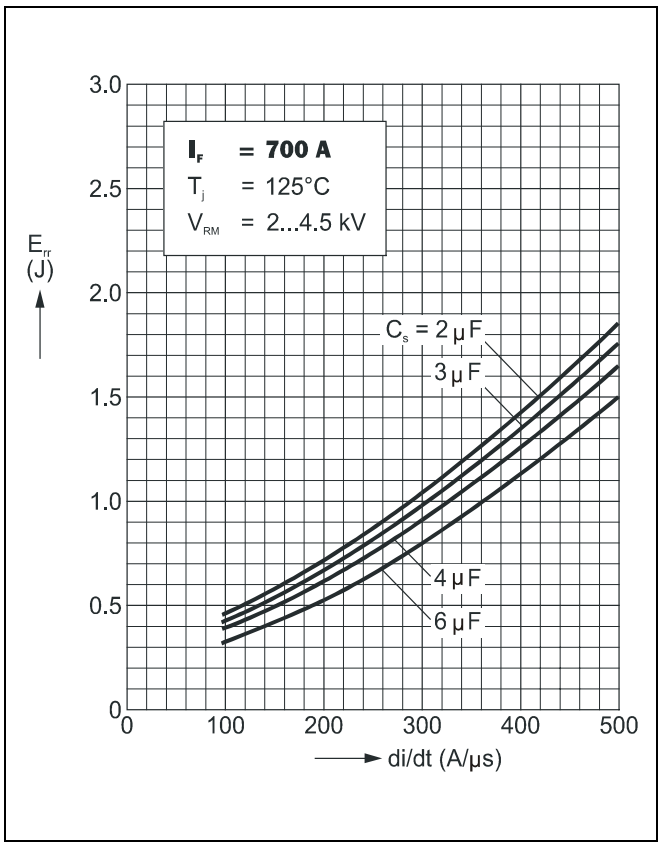

Fig. 10 Turn-off energy vs. turn-off di/dt for I_F = 700 A (max. values).

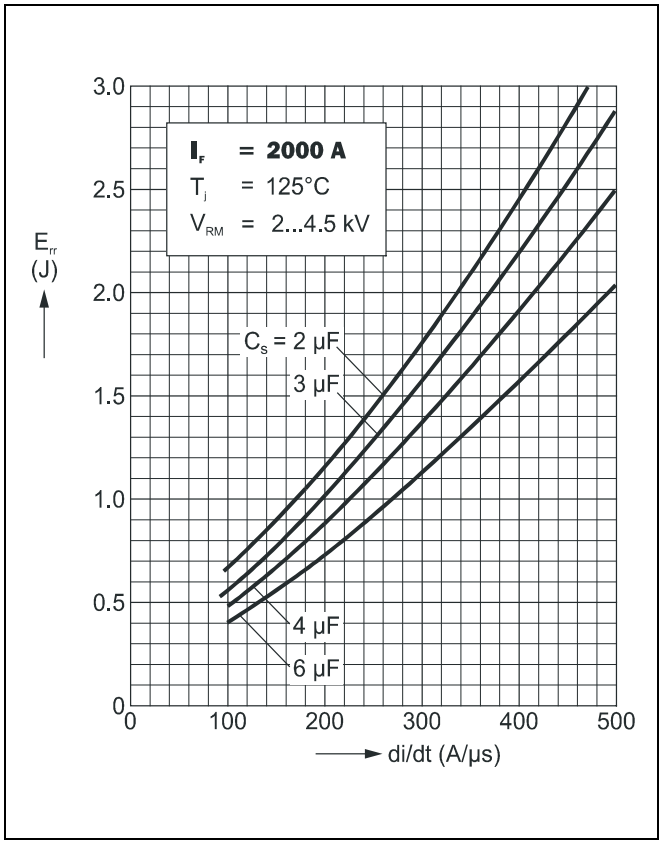

Fig. 11 Turn-off energy vs. turn-off di/dt for I_F = 2000 A (max. values).

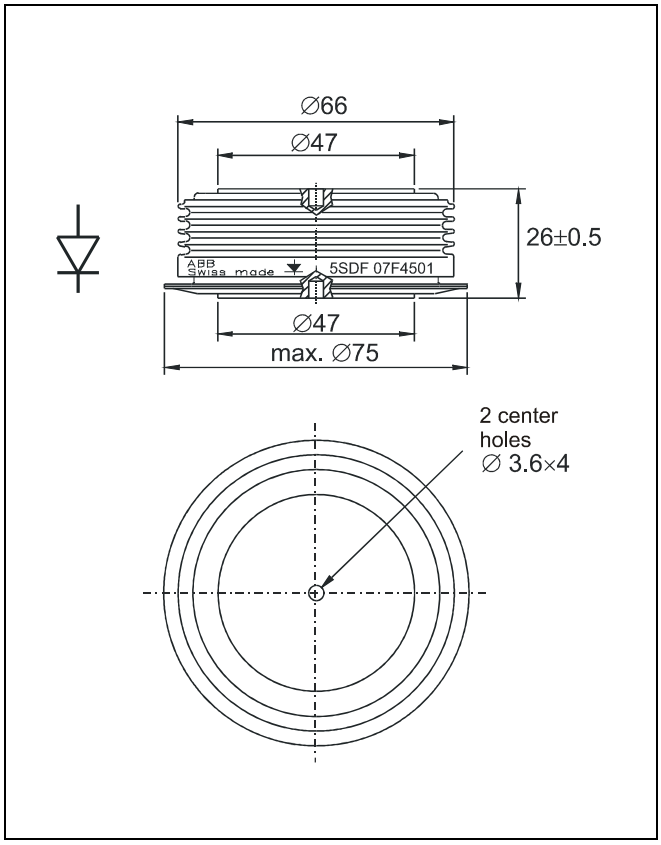

Fig. 12 Outline drawing. All dimensions are in millimeters and represent nominal values unless stated otherwise.

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